LTKAK6 Series SMT0-218 - 6KA





Agency Approvals

Agency	Agency File Number
91	E128662

Maximum Ratings and Thermal Characteristics $(T_a=25^{\circ}C \text{ unless otherwise noted})$

Parameter	Symbol	Value	Unit
Operating Junction	T_{J}	-55 to 125	°C
Storage Temperature Range	T _{stg}	-55 to 150	C
Current Rating ¹	I _{PP}	6	kA
Typical Thermal Resistance Junction to Lead	R _{ej∟}	10	°C/W
Typical Thermal Resistance Junction to Ambient	$R_{_{\Theta JA}}$	50	°C/W

Note:

1. Rated min $I_{\mbox{\tiny PP}}$ measured with 8/20 $\mbox{\mu s}$ pulse.

Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Numbers	Standoff Voltage (V _{so})	Max. Reverse Leakage (I _R) @V _{so}		kdown Voltage @ I _T	Test Current I _T	Max. Clamping Voltage V _c @ (I _{PP})	Max. Temp Coefficient of V _{BR}	Max. Capacitance 0V Bias 10kHz
	(V)	¨(μΑ) ັ	Min Volts	Max Volts	(mA)	Volts	(%/°C)	(nF)
LTKAK6-058C	58	10	64	70	10	110	0.1	6.5
LTKAK6-066C	66	10	72	80	10	120	0.1	5.5
LTKAK6-076C	76	10	85	95	10	140	0.1	4.5

Note: Using 8/20 waveshape as defined in IEC 61000-4-5 2nd edition

Surge Ratings Max Peak Pulse Current (Ipp) Part (80/20µS) (10/350µS) (10/1000µS) Numbers (A) (A) (A) Min Min Min Тур LTKAK6-058C 6,000 900 1,100 430 LTKAK6-066C 6,000 900 1,100 430 LTKAK6-076C 900 1,100 430 6,000



The LTKAK6 series offers superior clamping characteristics over standard S.A.D. technologies by virtue of the Littelfuse FoldbakTM technology, which provides a clamping voltage lower than the avalanche voltage (but above the rated working voltage). Therefore, any voltage rise due to increased current conduction is contained to a minimum, providing the best possible protection level. This LTKAK6 series can be combined in series or parallel solutions to offer various clamping levels and surge withstand options. The LTKAK6 SMT package provides a more compact PCB layout than typical through-hole AK TVS components.

Features

- High Power TVS designed in a surface mount and compact SMTO-218 package
- Patent pending package design
- Foldbak[™] Technology for superior clamping characteristics
- Tube or tape and reel pack options available
- Ideal for automatic pick and place assembly and reflow process to reduce the manufacturing cost and increase the soldering quality as compared to axial leaded packages

- Low clamping and slope resistance.
- Sharp breakdown voltage.
- Meet MSL level1, per J-STD-020, LF maximum peak of 245°C
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)
- UL Recognized compound meeting flammability rating V-0

I-V Curve Characteristics



P_{PPM} Peak Pulse Power Dissipation --Max power dissipation V_R Stand-off Voltage --Maximum voltage that can be applied to the TVS without operation V_{BR} Breakdown Voltage --Maximum voltage that flows though the TVS at a specified test current (I_T) V_c Clamping Voltage --Peak voltage measured across the TVS at a specified lppm (peak impulse current) I_R Reverse Leakage Current -

Current measured at $V_{_{\rm B}}$

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)



Pulse Waveform



Peak Power Derating



Please contact Littelfuse for reliability or FIT/MTBF data , the performance is subject to vary and depends on the end customers' application condition.



TVS Diode Datasheet

Soldering Parameters

Reflow Cond	ition	Lead–free assembly	
Pre Heat	- Temperature Min (T _{s(min)})	150°C	
	- Temperature Max (T _{s(max)})	200°C	
	- Time (min to max) (t _s)	60 - 180 secs	
Average ram	3°C/second max		
T _{S(max)} to T _A - I	3°C/second max		
Reflow	- Temperature (T _A) (Liquidus)	217°C	
nellow	- Time (min to max) (t _s)	60 – 150 seconds	
Peak Temperature (T _P)		245 ^{+0/-5} °C	
Time within 5°C of actual peak Temperature (t _p)		30 seconds Max	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T _P)		8 minutes Max.	
Do not excee	d	245°C	



Flow/Wave Soldering (Solder Dipping)

Peak Temperature :	260°C
Dipping Time :	10 seconds
Soldering :	1 time

Physical Specifications

Weight	Contact manufacturer
Case	Epoxy encapsulated
Terminal	Tin plated lead, solderable per MIL-STD-202 Method 208



Part Marking System





Physical Specifications

High Temp Storage	JESD22-A103
HTRB	JESD22-A108
MSL	JESDEC-J-STD020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-B106



Dimensions – SMTO-218





Dimension	Inc	hes	Millimeters		
Dimension	Min	Max	Min	Max	
Α	0.621	0.655	15.78	16.63	
В	0.529	0.594	13.43	15.09	
С	0.544	0.561	13.83	14.24	
D	0.273	0.285	6.94	7.24	
E	0.702	0.737	17.82	18.72	
F	0.567	0.587	14.40	14.90	
G	0.087	0.126	2.20	3.20	
н	0.193	0.222	4.89	5.65	
J	0.028	0.033	0.72	0.85	
L	0.400	0.440	10.17	11.17	
М	0.073	0.112	1.85	2.85	
N	0.510	0.533	12.95	13.55	

Note: Coplanarity of solder side is controlled within 0.08mm.

Packaging

Part Number	Weight	Packing Mode	Base Quantity
LTKAK6-xxxC	4.34g	Tape & Reel – 32mm/13" tape	400
LTKAK6-xxxC-TP	4.34g	Tube Pack	100(25/Tube)



Tape and Reel Specification

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